

IN THE CLAIMS

Please amend the claims to read as follows:

Listing of Claims

1-19. (Canceled).

20. (New) A semiconductor device layout inspection method for inspecting formation defects that will occur in wires of a chip layout, the method comprising:

calculating the density of contact holes in the wires; determining that the layout of wires is defective when the calculated density is equal to, or greater than, a predetermined limitation value; and

correcting, when the layout of wires is determined to be defective, the layout of wires by decreasing the density of contact holes so that the density of contact holes becomes less than the predetermined limitation value without changing the size of the contact holes.